

REV	ECN NO.	DISCRIPTION	CHECKED/DATE	APPD/DATE

NOTES: 1. MATERIAL:

MOLDING: LCP UI94 V-0
CONTACT: COPPER ALLOY.

GOLD PLATED Min ON CONTACT AREA, 100u"
Min TIN (LEAD FREE) ON SOLDER AREA,

SHELL: SUS304-H, T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.

SHILD: SUS304-H, T=0.12±0.03mm

2. MECHANICAL:
INSERTION: 5~20N.
EXTRACTION: 8~20N AFTER TEST.

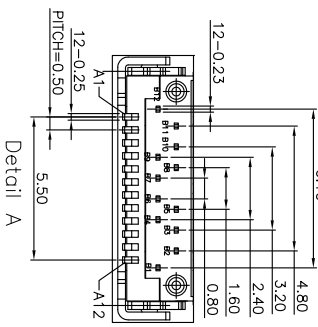
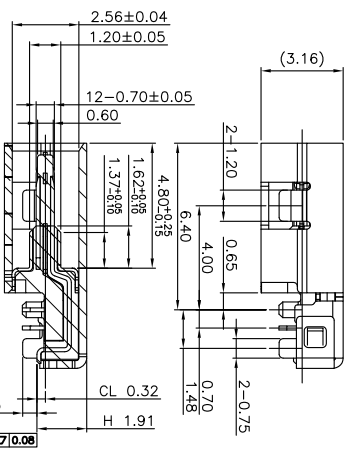
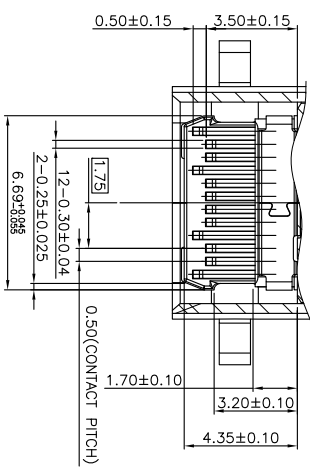
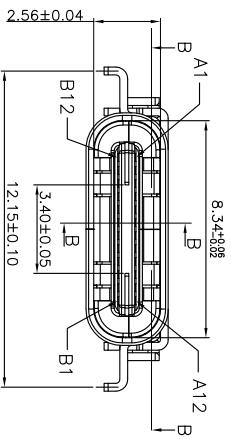
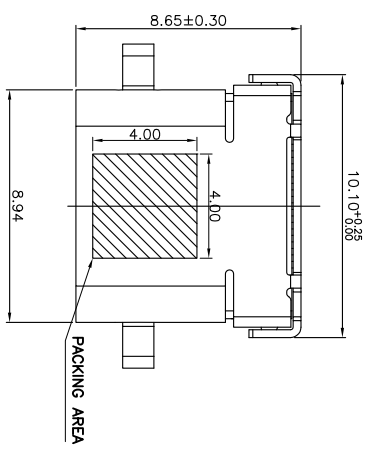
DURABILITY: 10000 CYCLES
3. ELECTRICAL:

CURRENT: 5A FOR VBUS;
1.25A FOR GND PIN.
0.25A FOR OTHER.

VOLTAGE: 20 V MAX
WITHSTANDING VOLTAGE: 100V AC R.M.S.

CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.

4. ENVIRONMENTAL
TEMPERATURE RANGE -25°C ~ +85°C



USCX-24FX-XXMX-35

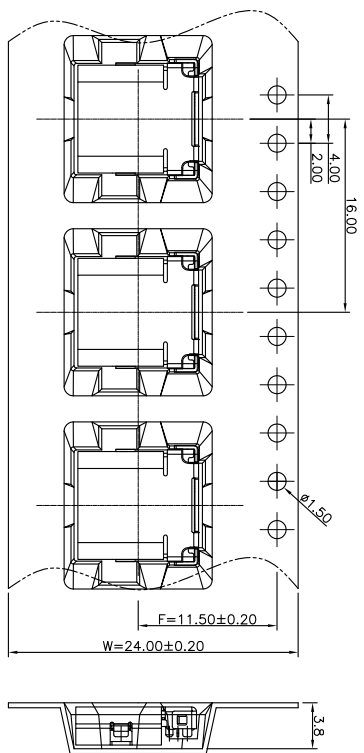
- 1-G.P
- 2-ROHS
- 3-REACH
- 4-HF/无卤
- 1-卷带包装
- 2-PC盒
- N-可焊锡
- S-锡
- T-无锡
- A-金
- K-黑色
- N-本色
- B-半金穿锡 1u"
- D-半金穿锡 5u"
- F-半金穿锡 15u"
- H-半金穿锡 30u"

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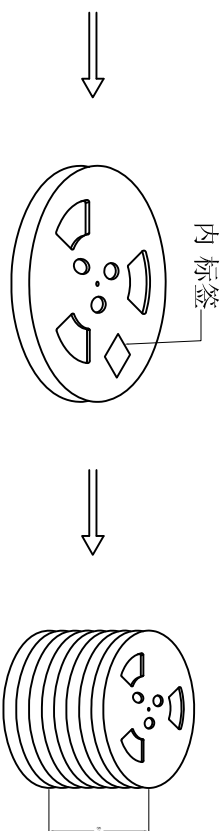
. X: ±0.25	X: ±1°	APP.	DWG NO.	TITLE	USB 3.1 C TYPE 沉板 DIP+SMT 成品
. XX: ±0.15	. X: ±0.5°	CHK.			短体8, 65L, 四脚插板
. XXX: ±0.05	. XX: ±0.02°	DGN			
UNIT mm		DWG		SERIES	
SCALE 1:1		SHEET: 1/1			
REV. A0					

1 2 3 4 5 6 A B C D E F

REV.	ECN NO.	DESCRIPTION	DRAWN/DATE	CHECKED/DATE	APPROVED/DATE

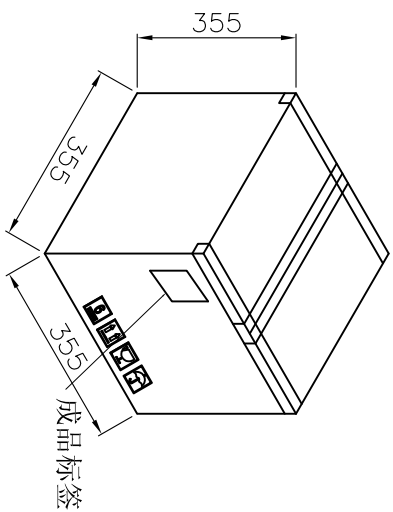


① 产品入载带示意图

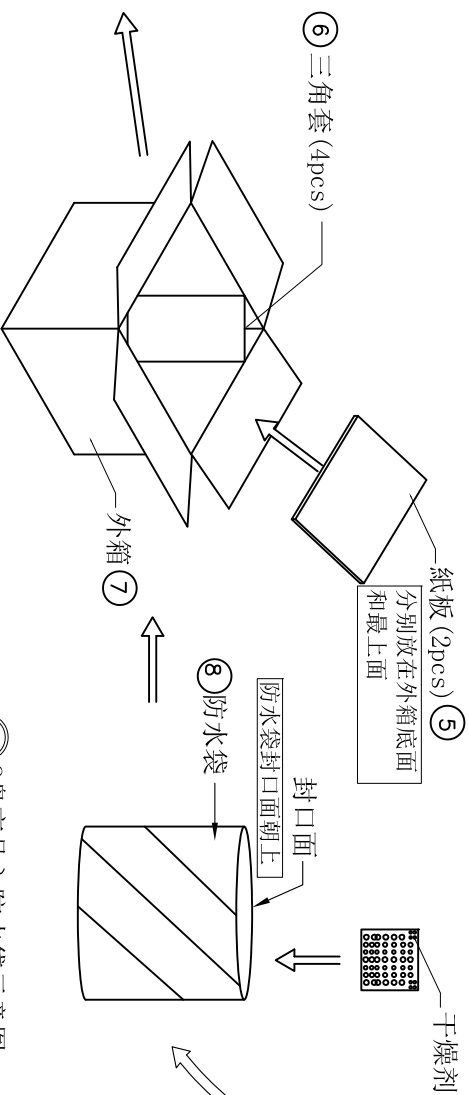


② 卷盘贴标签示意图

③ 8盘产品叠层示意图



⑥ 外箱封箱示意图



⑤ 产品入外箱示意图

④ 8盘产品入防水袋示意图

图三

包装说明:

1. 将检验好的成品;SMT朝下放入载带底部;每卷装1000PCS产品;具体如图一所示
2. 将包装好的产品;每盘必需贴上内标签;具体如图二所示
3. 将贴好内标签的产品每8盘叠一层装入防水袋中并加一包干燥剂;装好后将防水袋封好;具体如图三图四所示
4. 先将1pcs平卡放入纸箱底部;然后将装好产品的防水袋装入纸箱中;防水袋热熔封口,封口面需朝上;并将4PCS三角套分别装入4个角;如图五所示
5. 装好后将1pcs平卡放入纸箱最上面并封好纸箱及贴好相关标签;具体如图六所示;(产品包装的标签,如客户有要求,请按客户要求包装出货)
6. 载带前面留30PCS空格,后面留20PCS空格
7. COVER与CARRY剥离力:50-125g,速度:300mm/分钟左右,剥离角度:165°-180°

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.X:±0.50	X:±1°	APP.	PART NO	
.XX:±0.30	.X:±0.5°	CHK	TITLE	USB 3.1 C 沉板母座包装图
.XXX:±0.25	.XX:±0.02°	DGN	SERIES	
UNIT: mm		DWG		
SCALE: 1:1				
REV: AO	SHEET: 1/1			